

FIG. 1

SVI DOCKING STATION

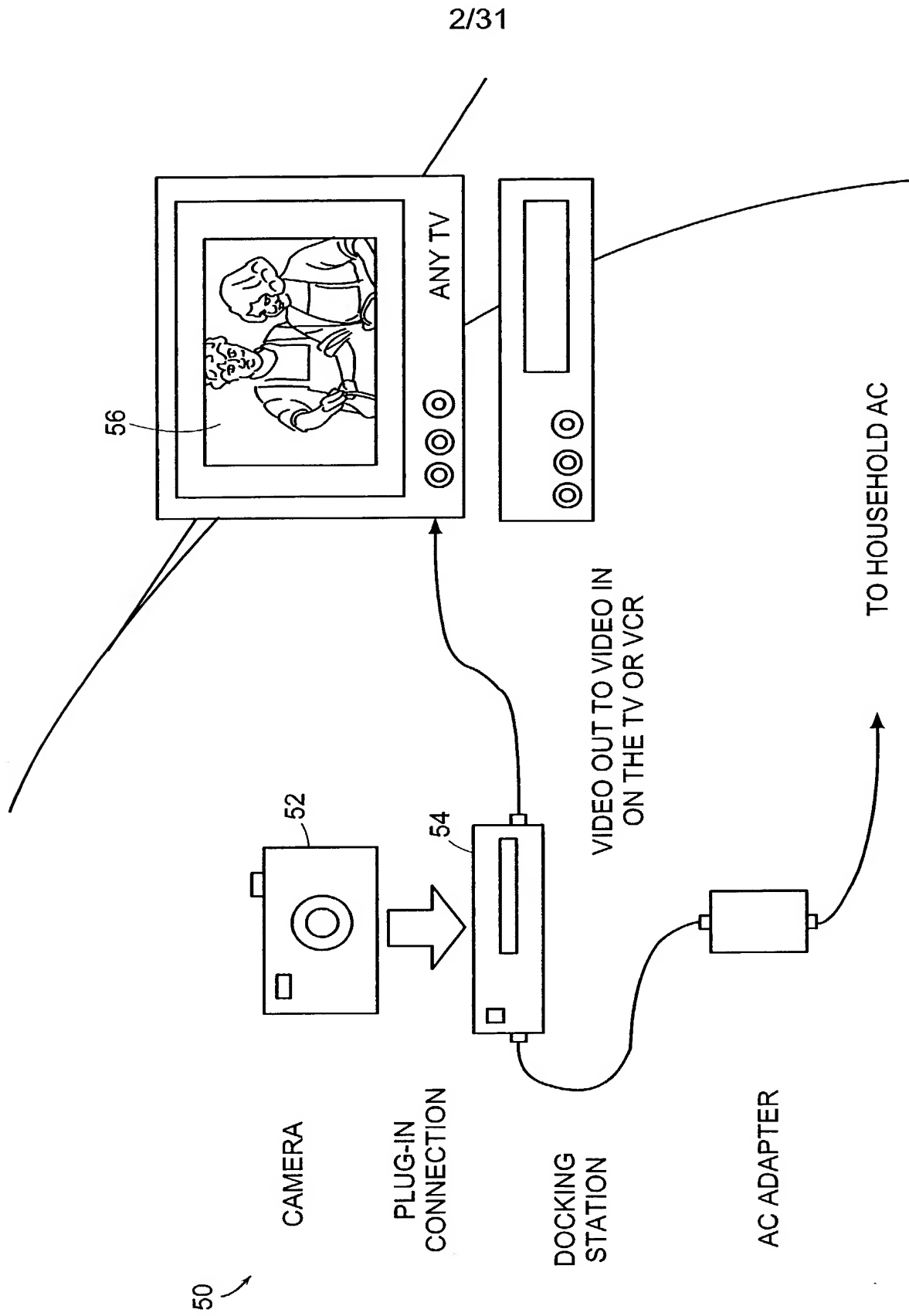


FIG. 2

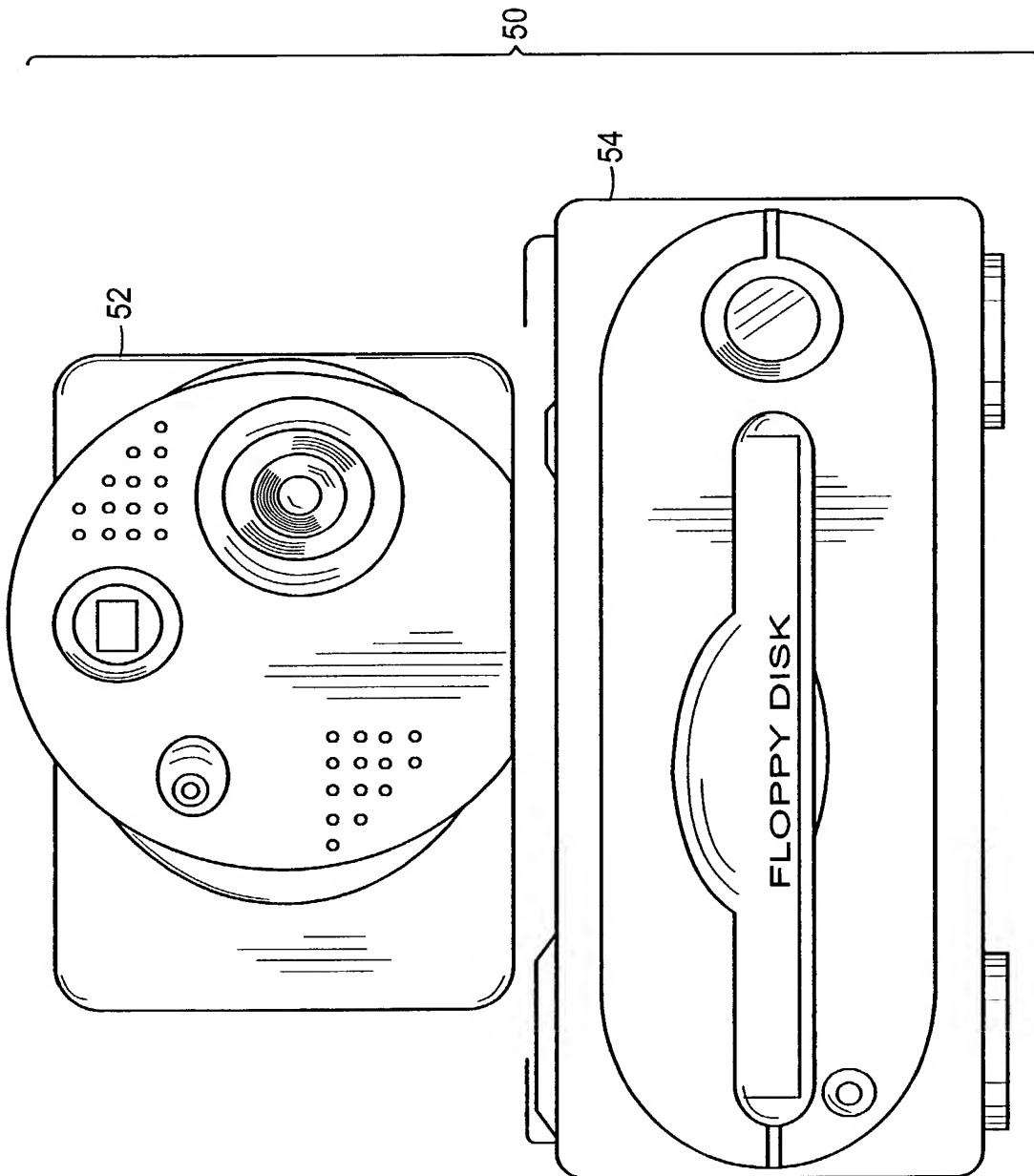


FIG. 3

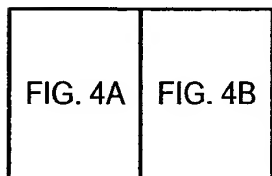
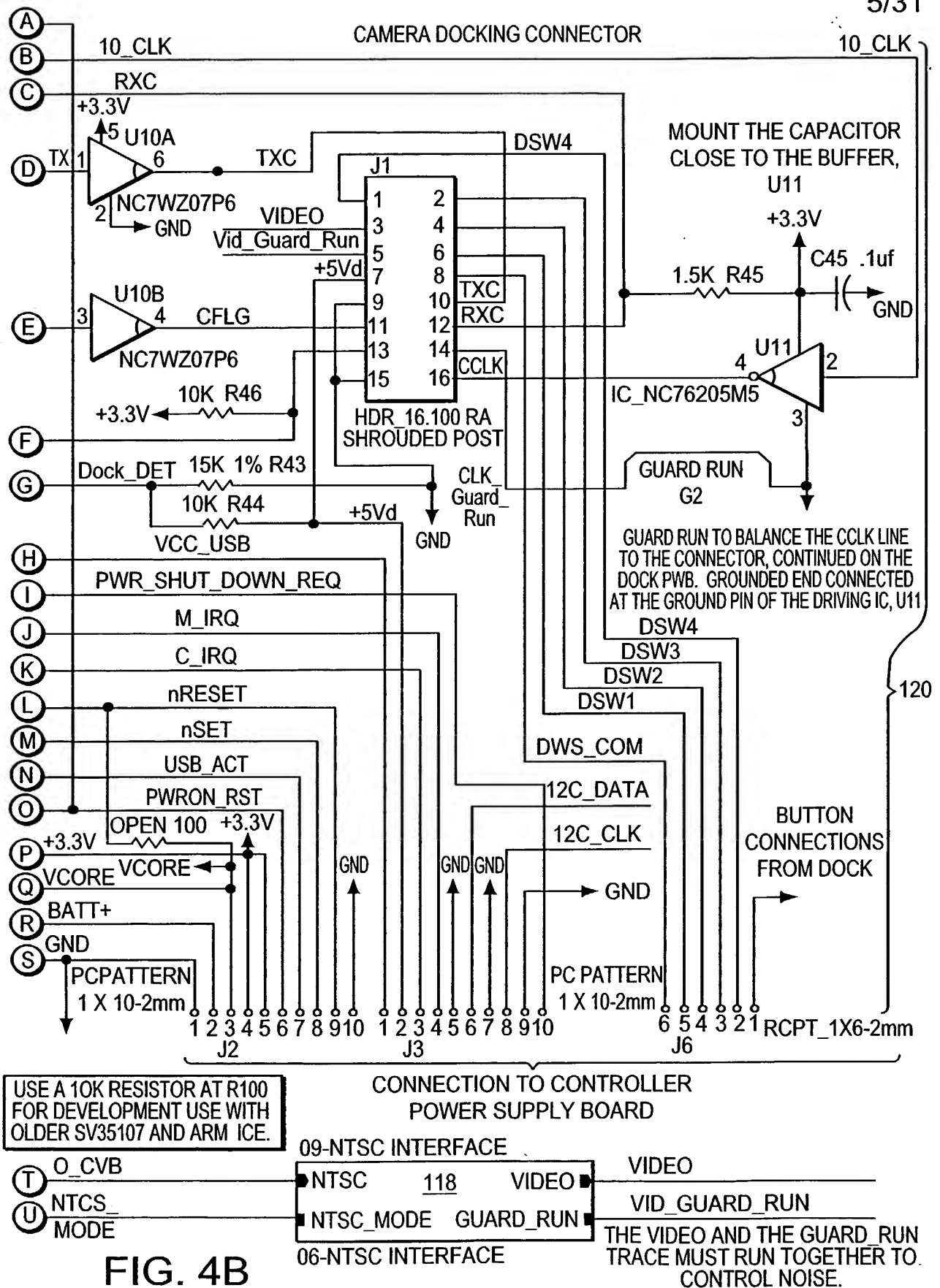
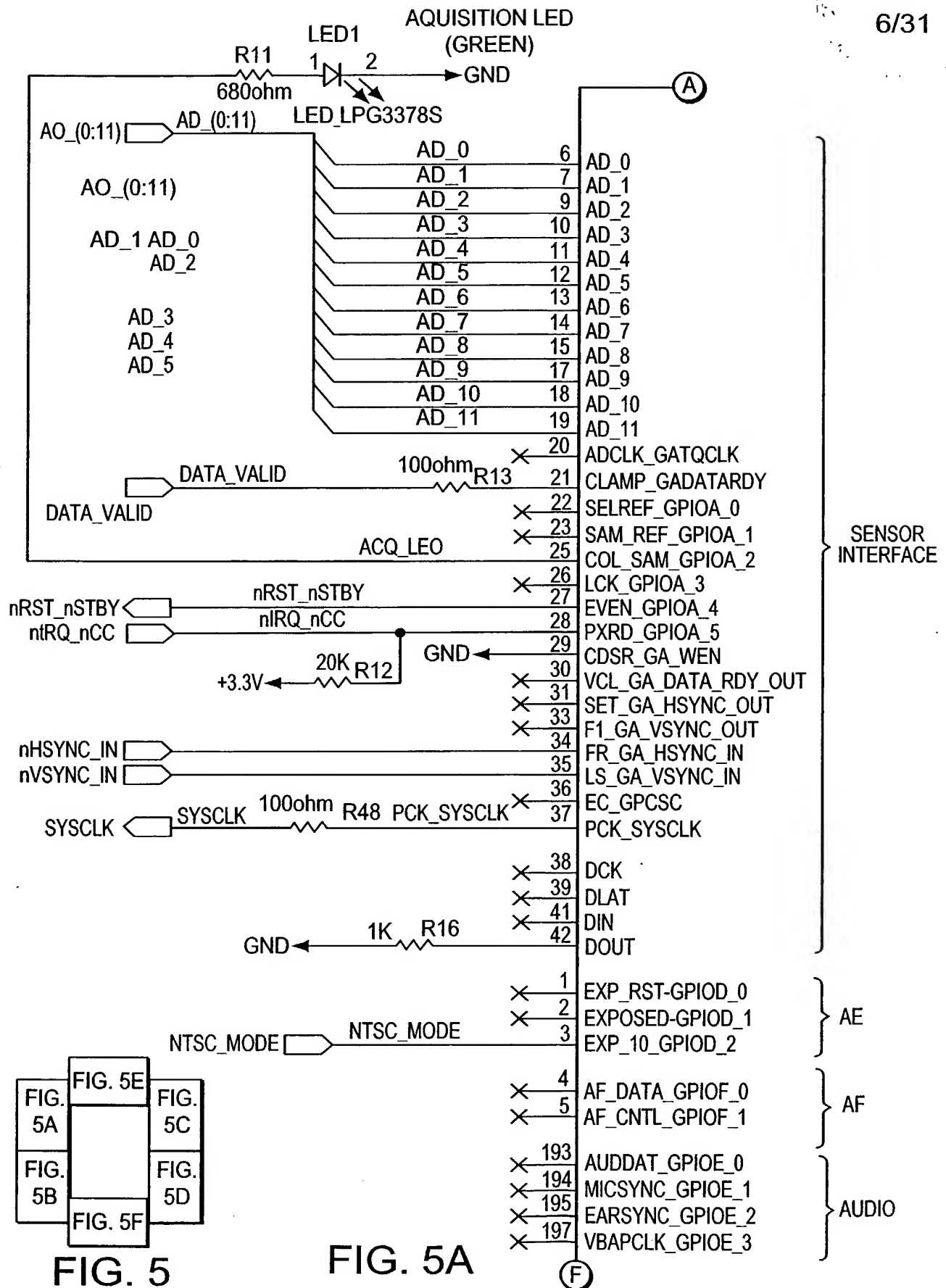


FIG. 4A





PCG_PADS_8

FLASH RDY 1 8

GND 2 7

GND 3 6

GND 4 5

FLASH D 49

FLASH T 50

FLASH I 51

+3.3V

FLASH CONNECTIONS

BATT+

J7 USB CONNECTOR

1 5 2 6 3 4

CON_USB_AMP_787780

GND

VCC_USB

27 R25

R26 27

R28 1.5K

+3.3V

U2A

4 S

14 V

5 Q

6 nQ

10 U2A

2 GND

3 C1

7 R103 OPEN

1 ID774ALVC74

PWRON_RST

PWRON_RST

SPARE FF

U3

VCORE

.01uf

C8

GND

5

4

2

3

GND

C_NC7S14M5

NOTE:

THESE PARTS ARE FOR USB SUSPEND MODE COMPATIBILITY. IF NOT REQUIRED THEY MAY BE OMITTED WITH A 0-470 OHM RESISTOR PLACED IN THE "OPEN" SPACE, R103.

TX TACK 68

RX TREQB 69

RTS 70

CTS 71

DSR GPIOH0 72

DTR GPIOH1 73

RI GPIOH2 74

1K R21

1K R23

191

192

65 USB_DN

64 USB_DP

USB_DATA_N

USB_DATA_P

FLASH_DRV_GPIOG_0

FLASH_INH_GPIOG_1

FLASH_TRIG_GPIOG_2

12C_DATA

12C_CLK

12C

UART

USB

F

E

FIG 5B

FIG. 5B

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NOTE: TGND IS A PORTION OF THE GROUND PLANE PROTECTED WITH CUTS. IT IS NOT A SEPARATE RUN!

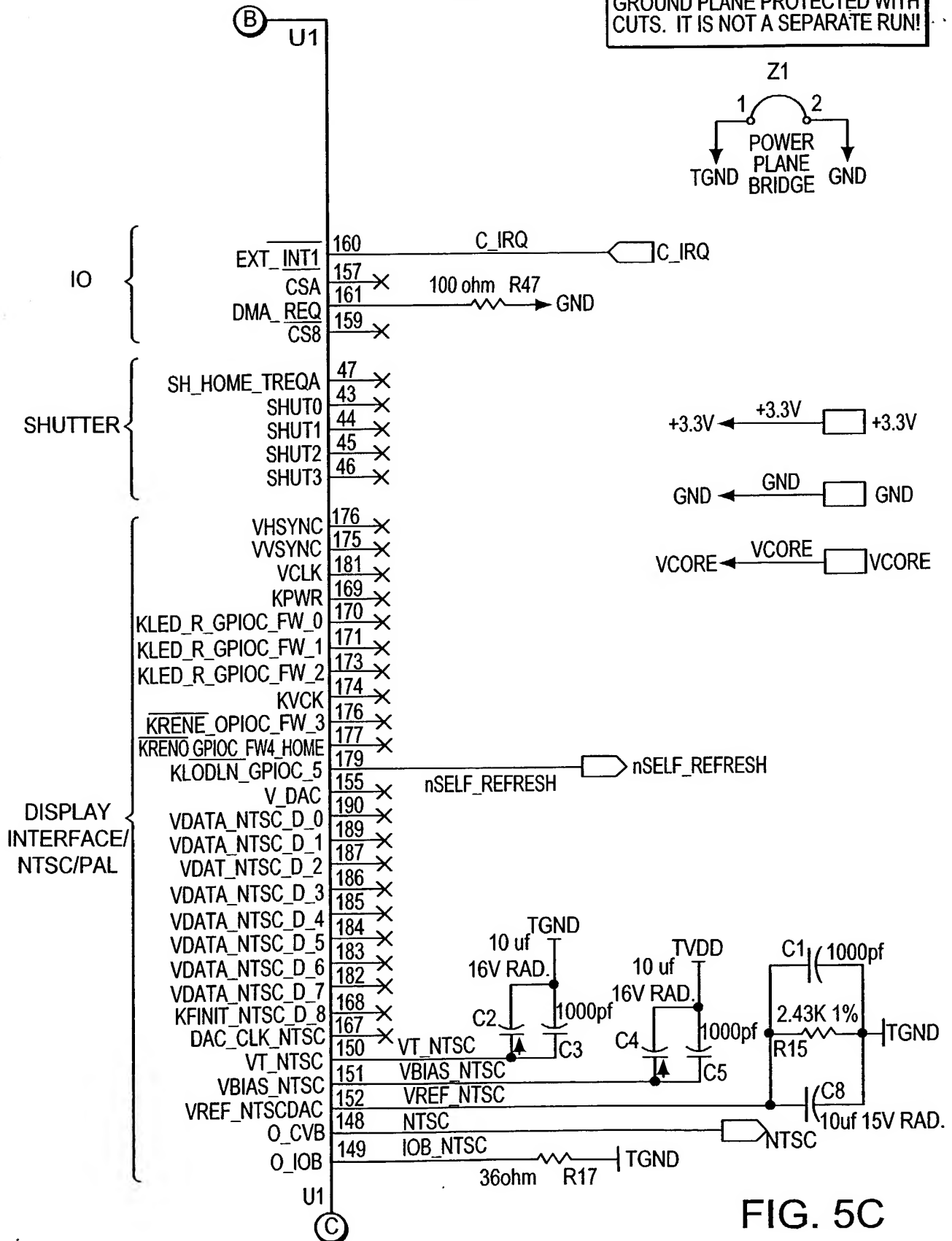


FIG. 5C

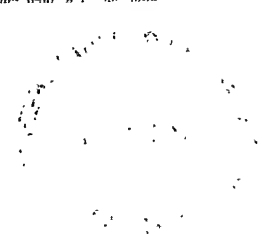


FIG. 5D

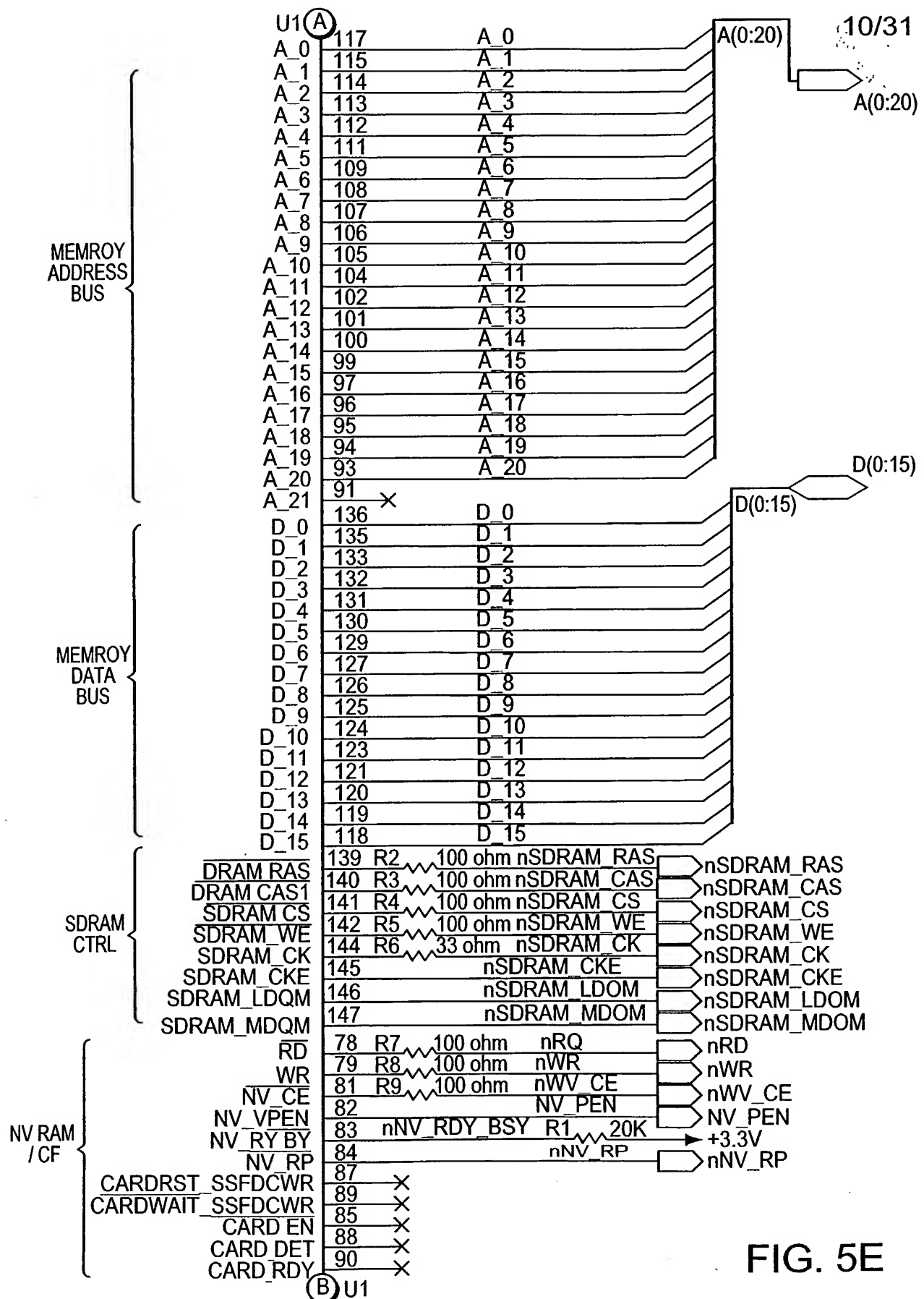
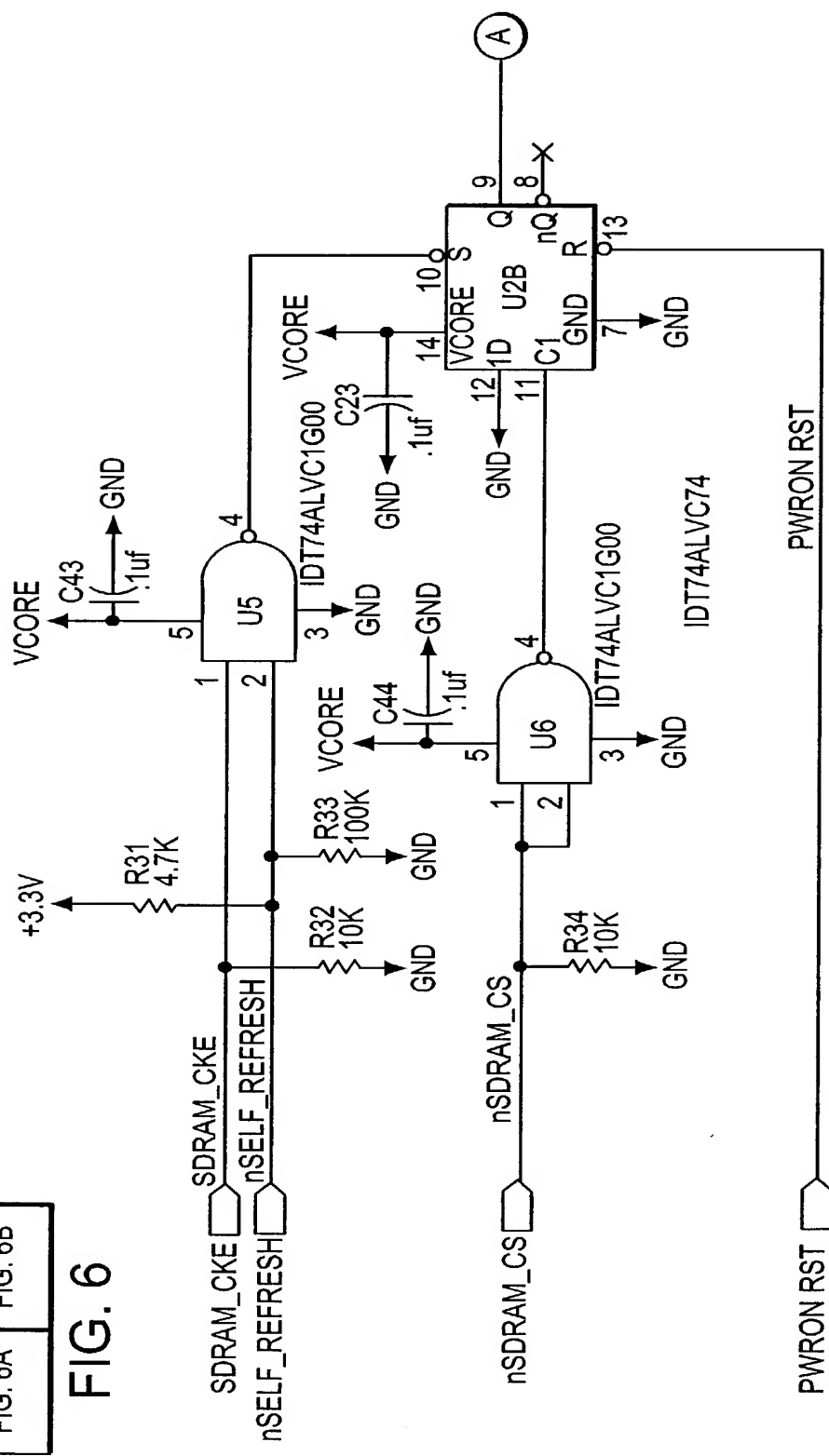




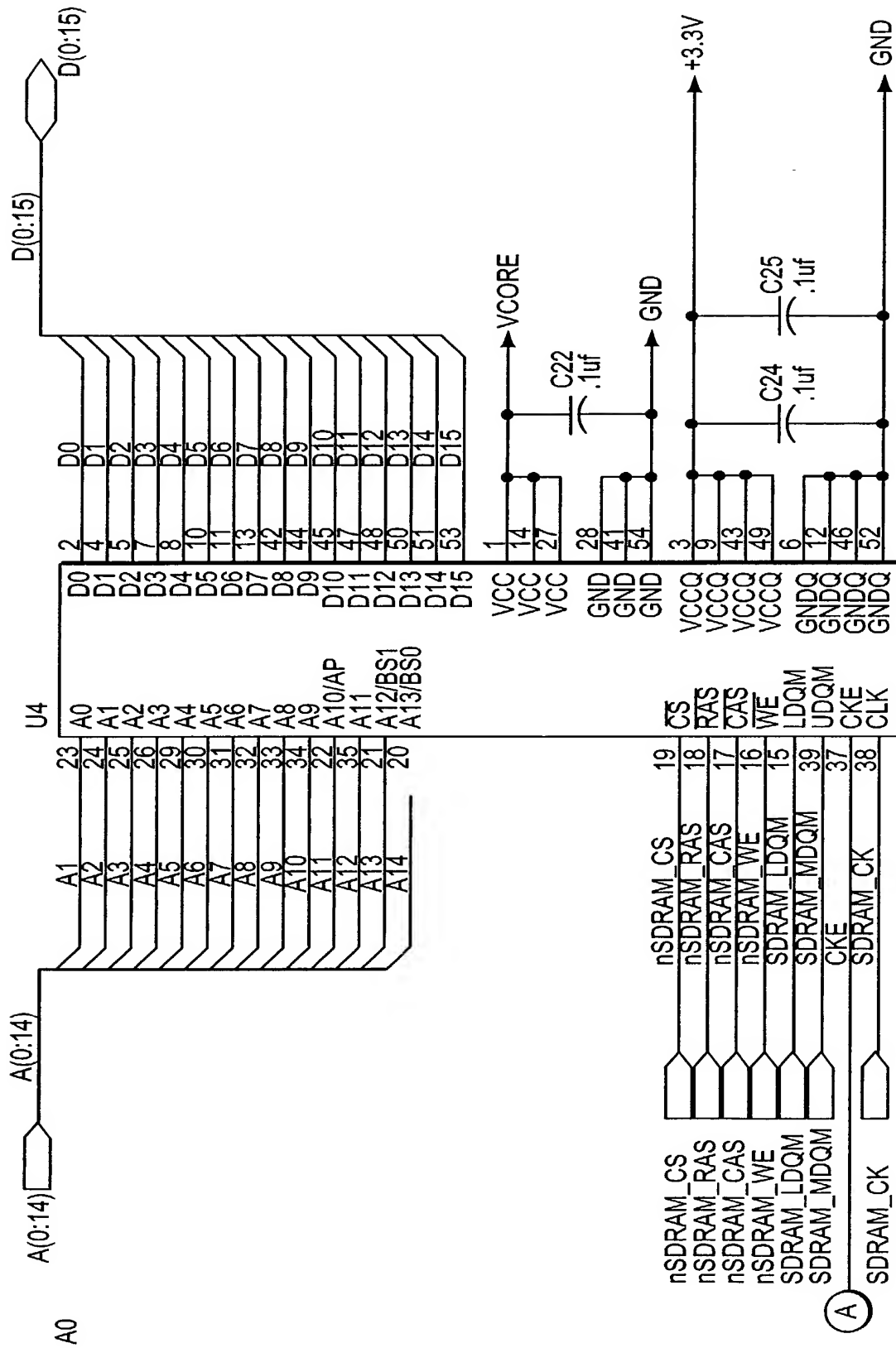
FIG. 6A	FIG. 6B
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FIG. 6



LOW POWER SDRAM SHOULD BE USED. POWER CONSUMPTION WHEN THE CAMERA IS SHUT DOWN DEPENDS ON THE SDRAM CONSUMPTION IN SELF REFRESH MODE AS THE MAJOR COMPONENT OF QUIESCENT CONSUMPTION.

FIG. 6A



SDRAM 4 MEG x 16 - LOW POWER

4M x 16 SDRAM SHOWN, CAN ALSO USE
1M x 16 WITHIN THE SAME FOOTPRINT.

NOTE: THIS DESIGN REQUIRES SDRAM PARTS
WITH ISOLATED V_{cc} AND V_{ccq} ON CHIP.

FIG. 6B

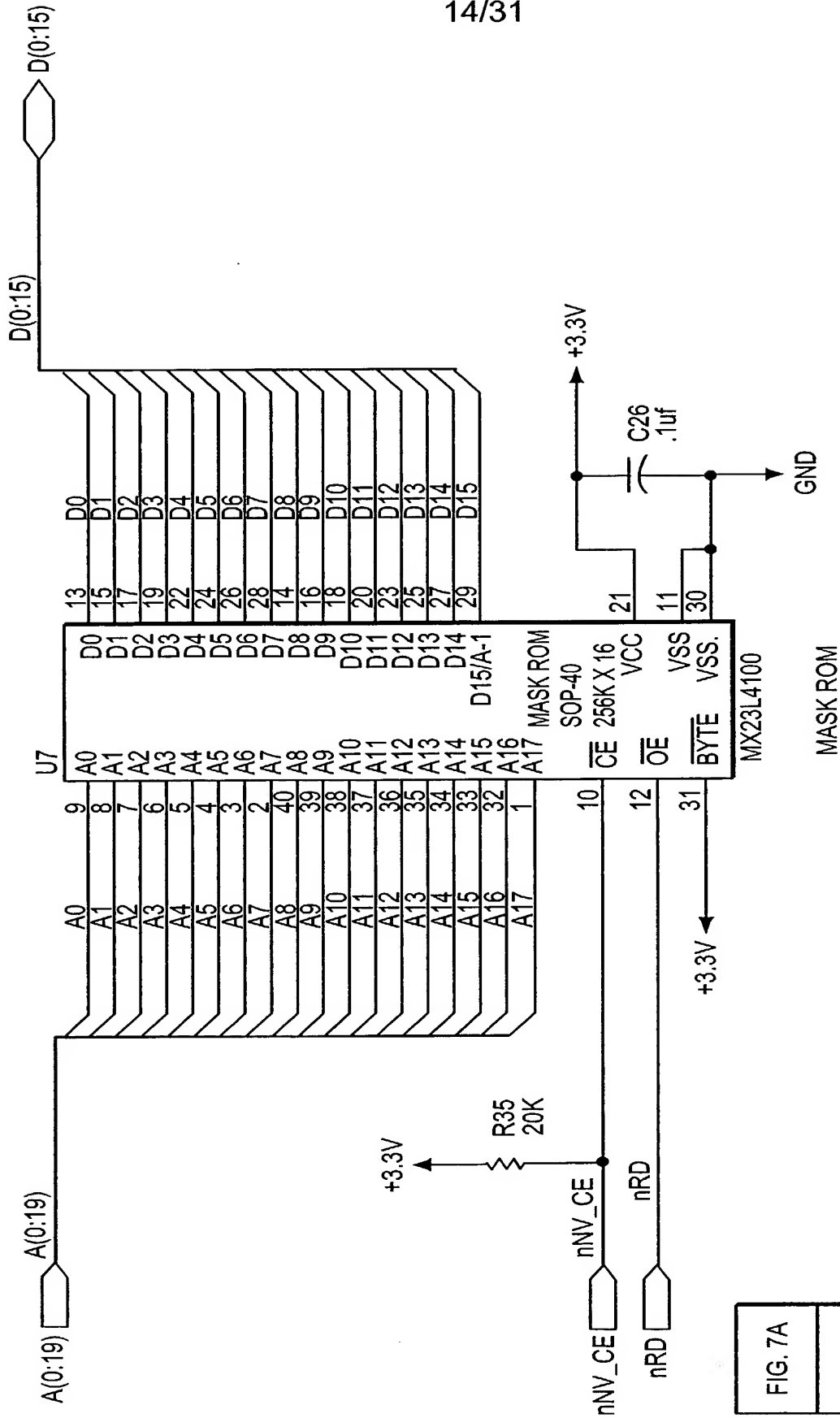


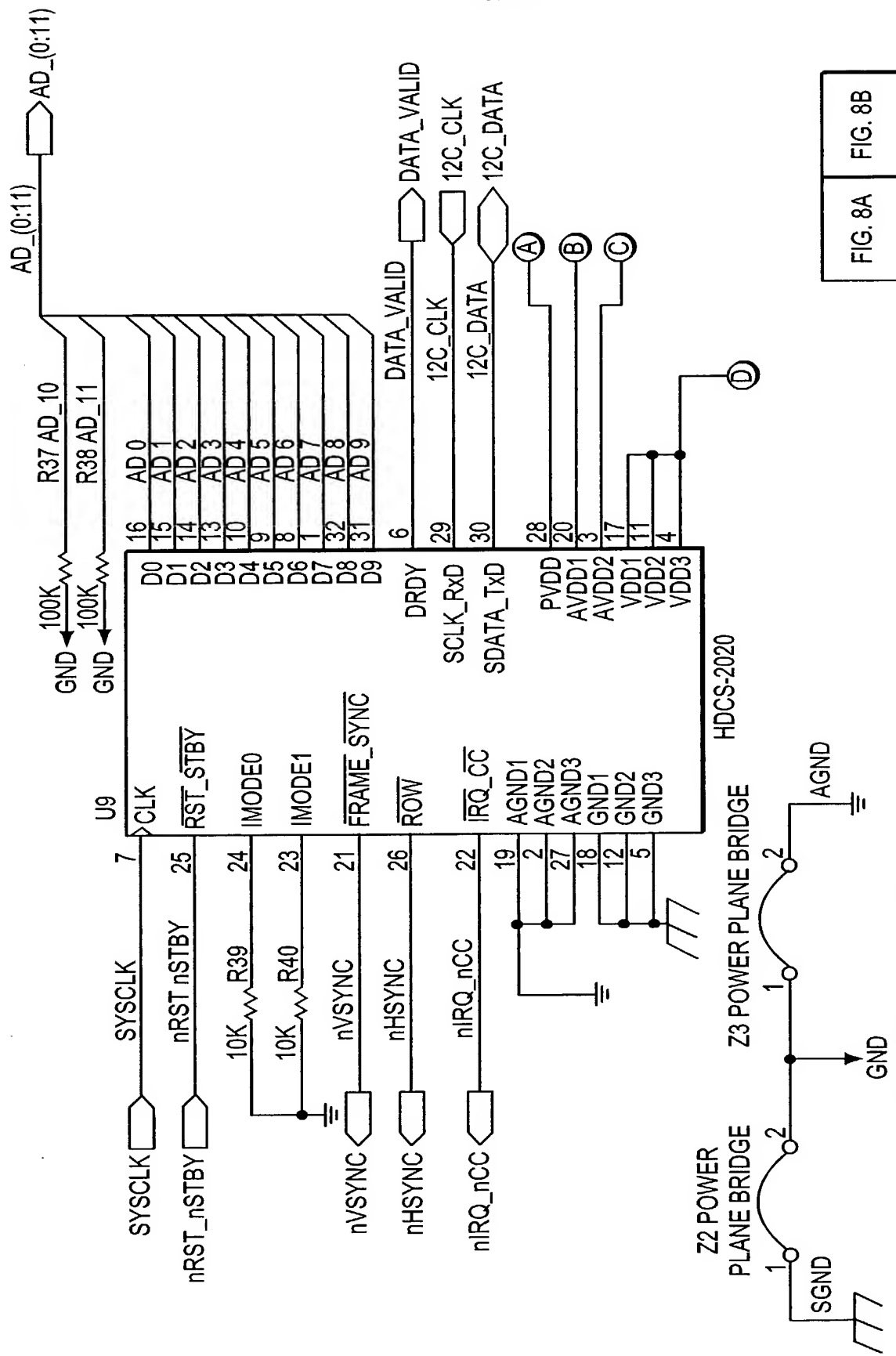
FIG. 7A
FIG. 7B

FIG. 7A

FIG. 7



FIG. 7B



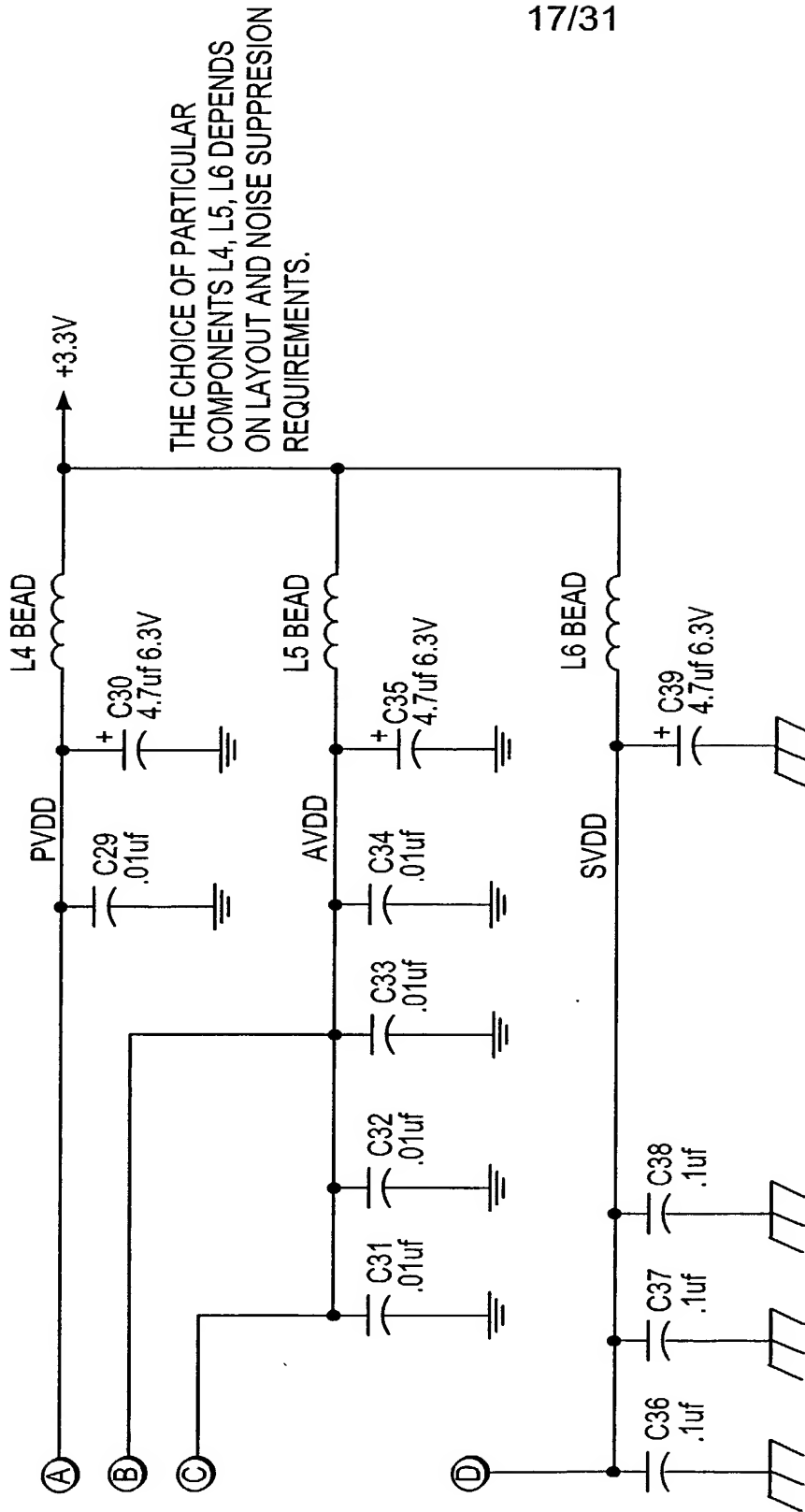
AGND AND SGND ARE PORTIONS OF THE GROUND PLANE PROTECTED WITH CUTS. THEY ARE NOT SEPARATE RUNS!

FIG. 8A

FIG. 8A FIG. 8B

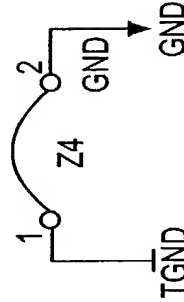
FIG. 8

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PLACE THESE CAPACITORS AND INDUCTORS (BEADS) AS CLOSE AS POSSIBLE TO THEIR RELEVANT PINS ON THE SENSOR PACKAGE. THIS GENERALLY REQUIRES MOUNTING THESE PARTS ON THE BACK OF THE BOARD BEHIND THE SENSOR TO ALLOW LENS MOUNTING. DOUBLE UP VIAS WHERE POSSIBLE, ESPECIALLY THE GROUND PLANE CONNECTIONS.

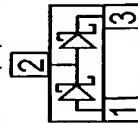
FIG. 8B



**TGND IS A PORTION OF THE GROUND PLANE
PROTECTED WITH CUTS. SEE CLARITY SHEET.
IT IS NOT A SEPARATE RUN!**

9
G.
F

NOTE:
THE DIODE PIN NUMBERING SHOWN HERE IS
NON-STANDARD. MAKE SURE THE PCB LAYOUT
MATCHES THE DIODE(S) USED IN YOUR DESIGN.



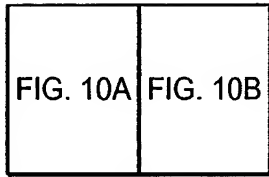
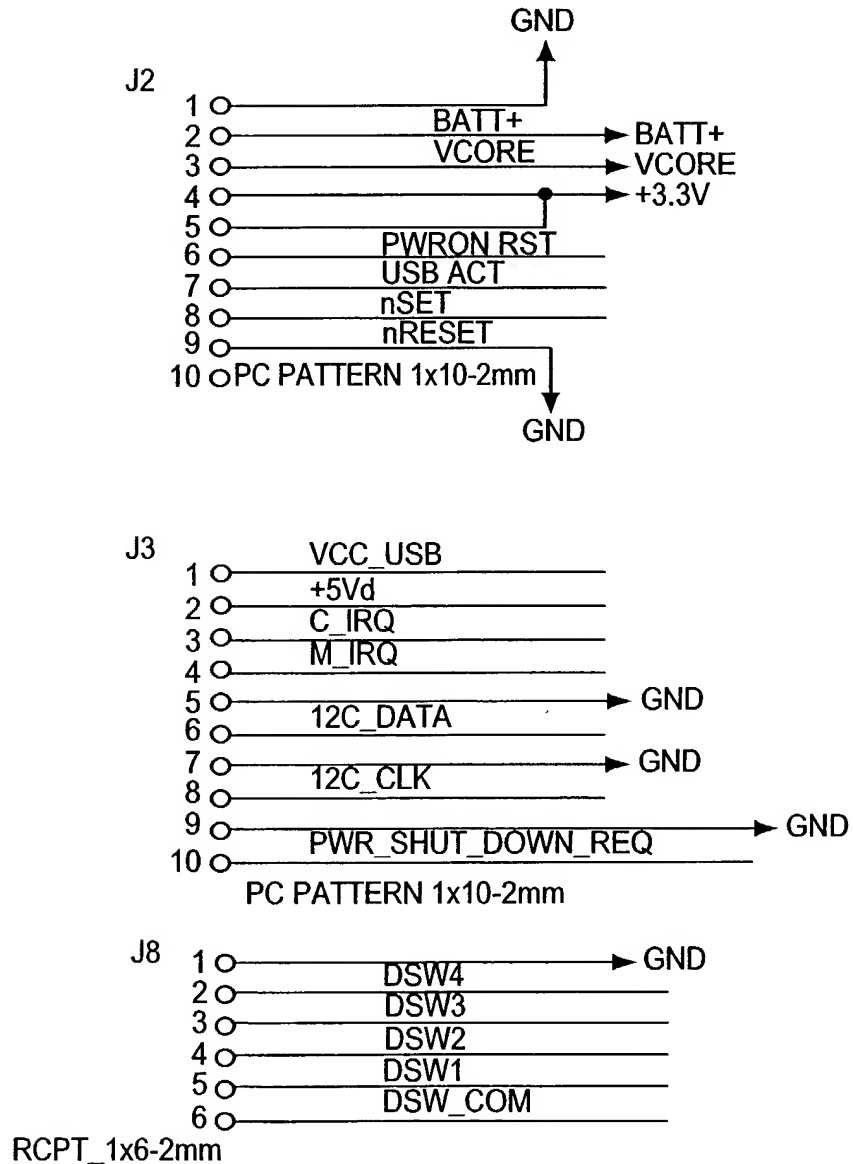


FIG. 10

MAIN BOARD CONNECTIONS



NOTE:

USE VERY WIDE TRACES FOR BATT+, +5Vd, VCORE, VBB AND THE +3.3V POWER PATH, PREFERABLY ON A POWER PLANE

FIG. 10A

10



FIG. 10B

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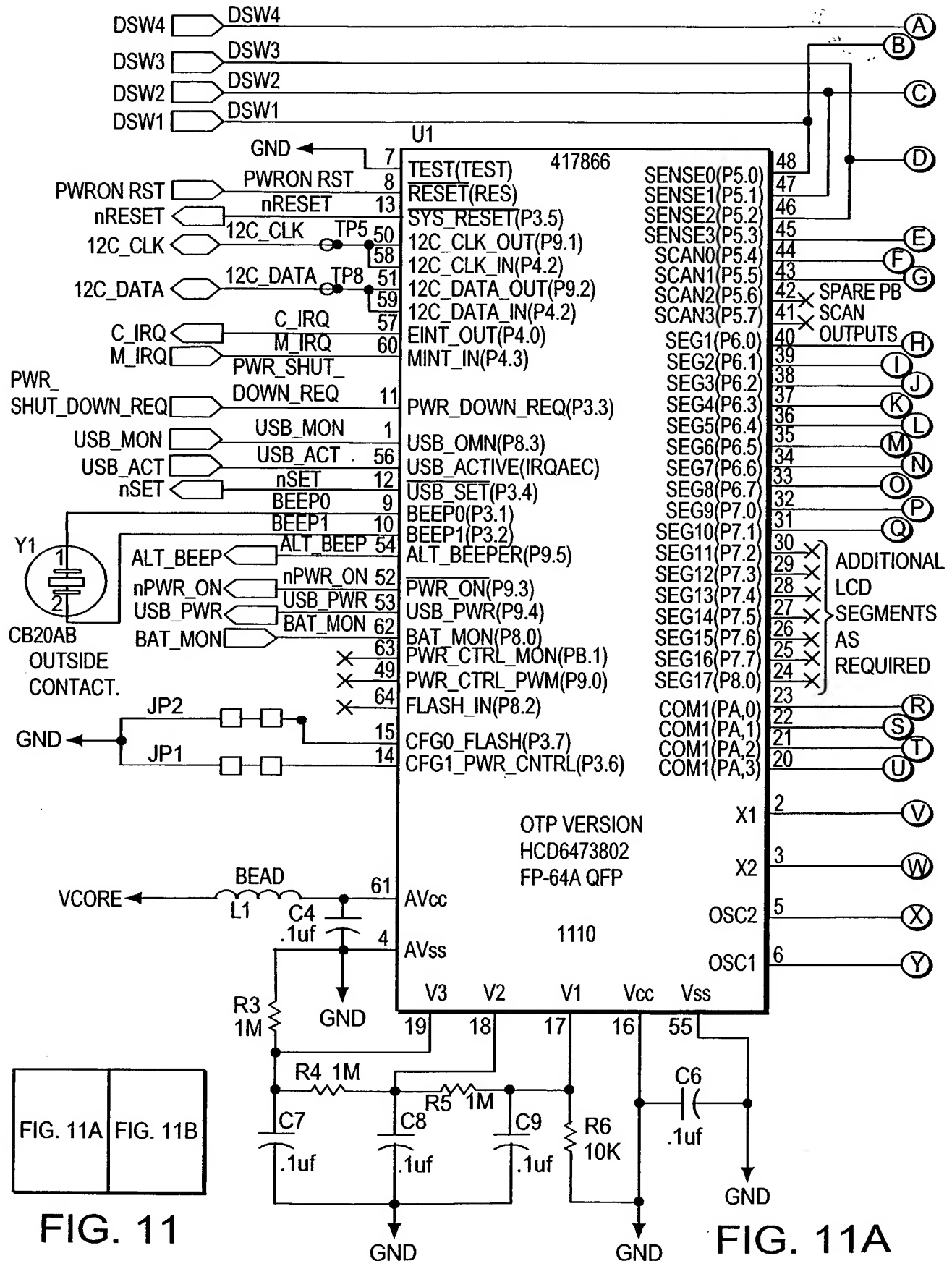
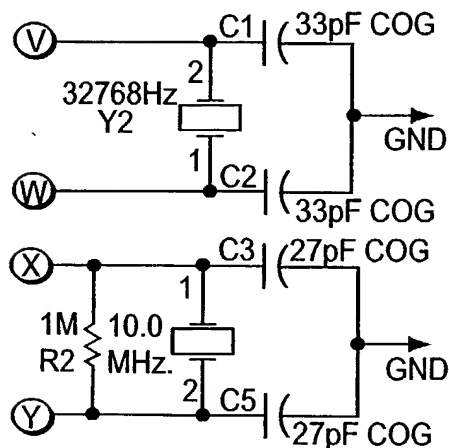
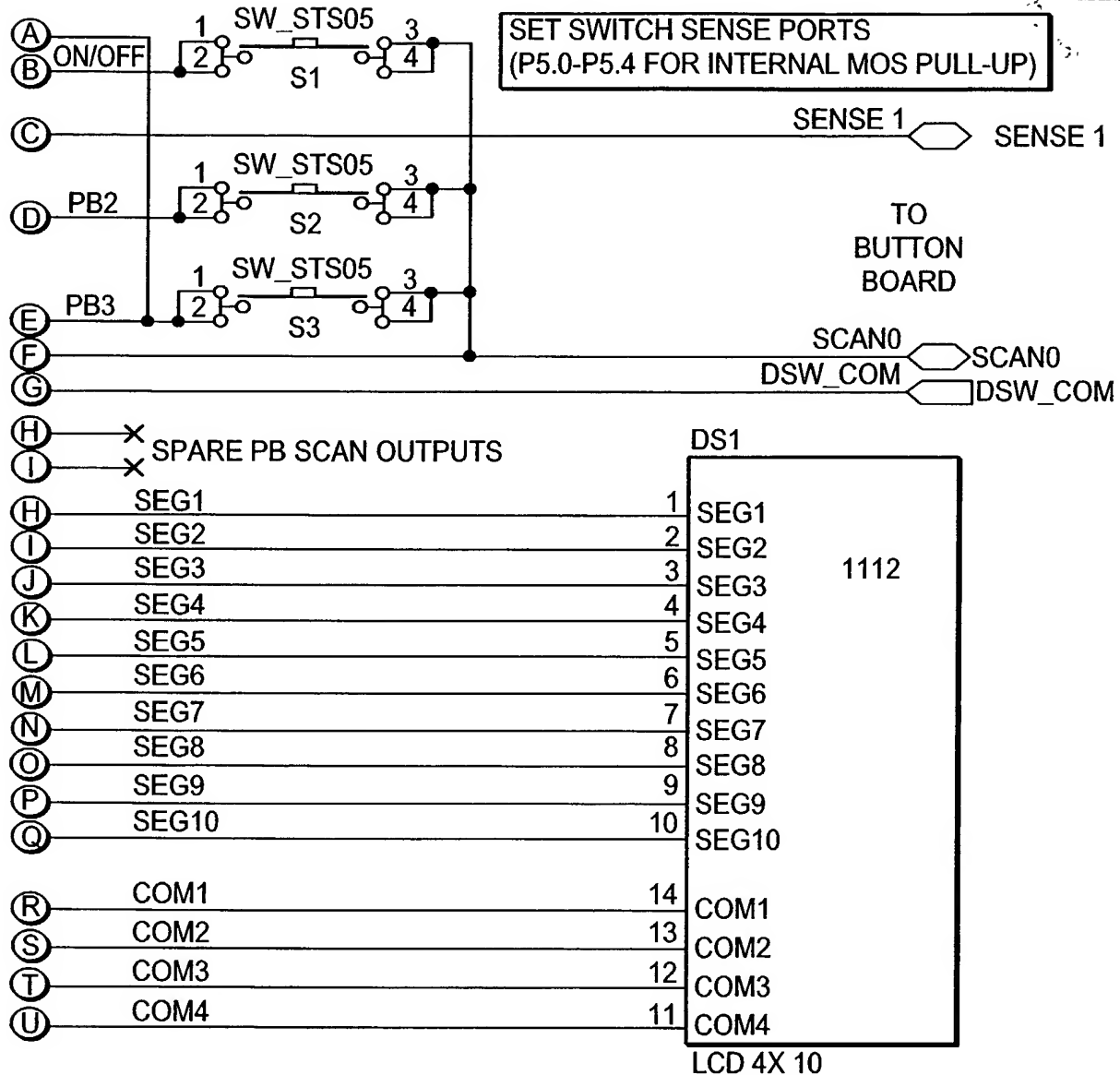


FIG. 11A

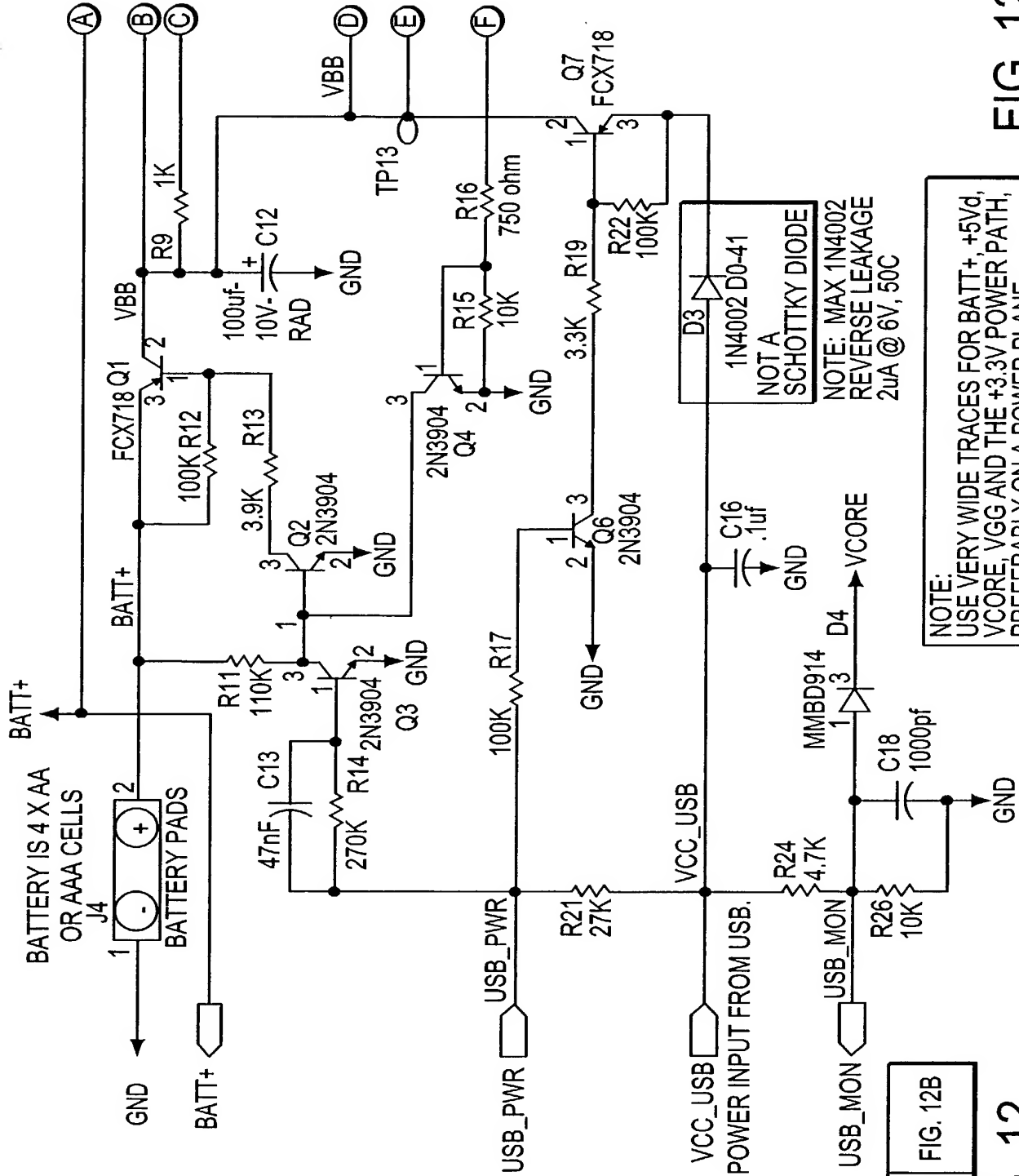
FIG. 11

FIG. 11A



- NOTES:**
1. SET UNUSED PORT PINS TO OUTPUT LOW.
 2. V_{CORE} IS USED AS THE ADC REFERENCE BY THE CONTROLLER.
 3. KEEP CRYSTAL AND RESONATOR CLOSE TO THE IC, SEE DATA SHEET.
 4. USE THE INTEGRAL PULL UP IN THE SWITCH PORTS.
 5. ON STARTUP USE P3.4 TO SET THE USB_ACT FLIP-FLOP BEFORE ENABLING THE IRQ TO SENSE USB DATA ACTIVITY.
 6. THE H8/3802 IC SHOWN IS THE OTP VERSION FOR DEVELOPMENT ONLY. FOR PRODUCTION USE THE MASK ROM VERSION, HD6433800H OR THE LOWEST COST COB VERSION; HCD6433800-(***).
 7. SET PORT 9 TO HIGH CURRENT MODE.

FIG. 11B



NOTE:
USE VERY WIDE TRACES FOR BATT+, +5Vd,
VCORE, VGG AND THE +3.3V POWER PATH,
PREFERABLY ON A POWER PLANE

FIG. 12A

FIG. 12A FIG. 12B

FIG. 12

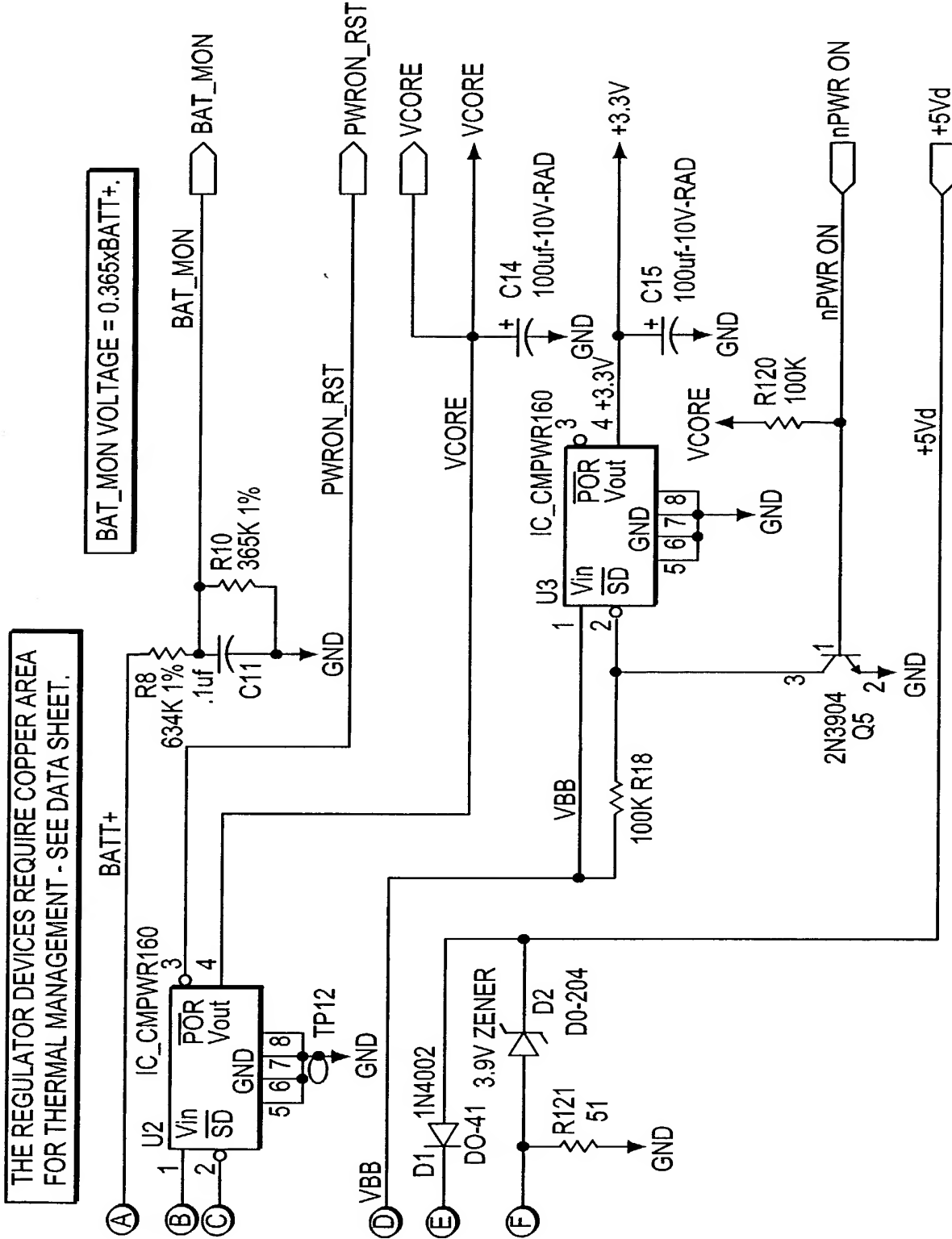
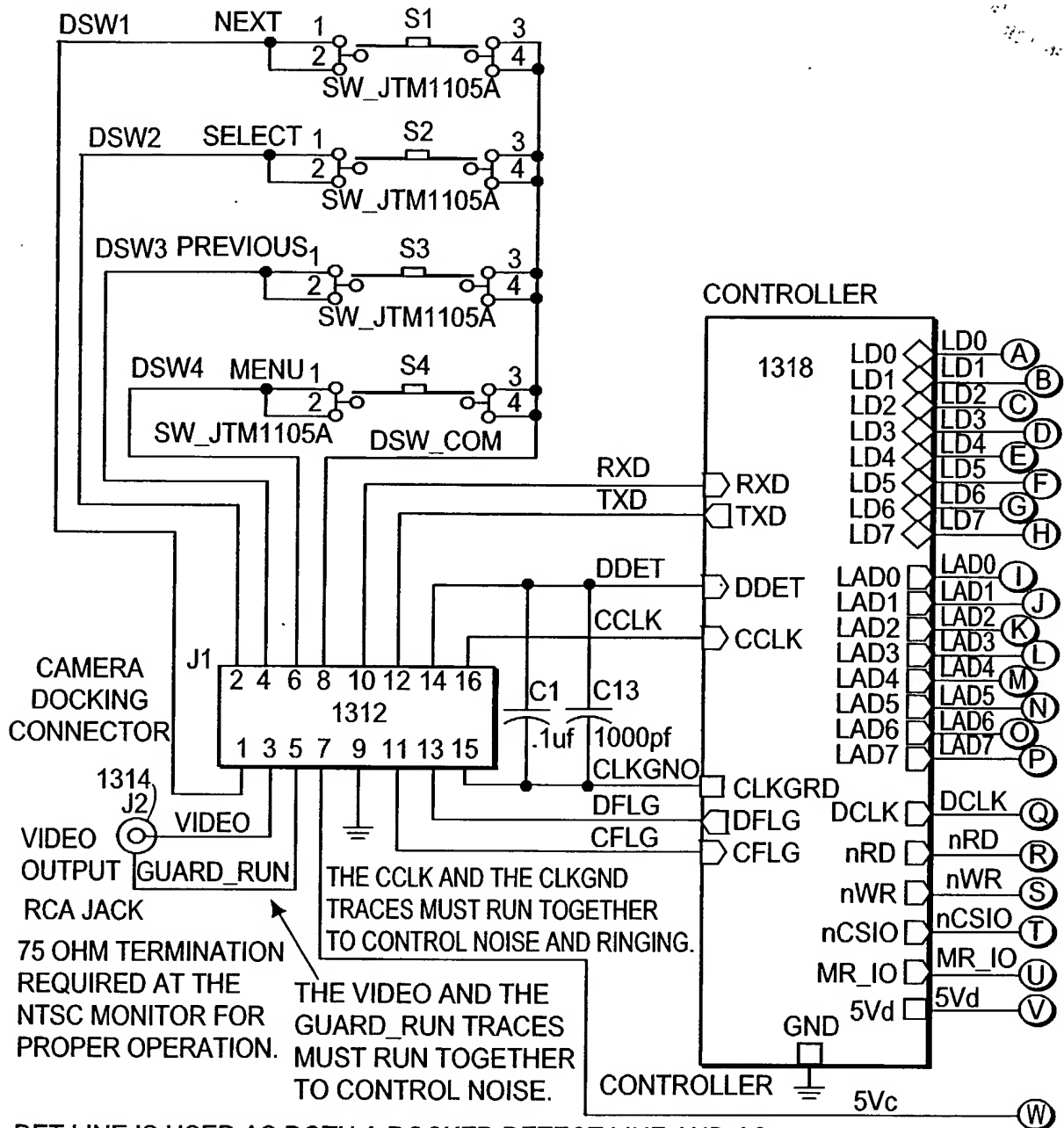


FIG. 12B

POWER INPUT FROM DOCK.

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DET LINE IS USED AS BOTH A DOCKED DETECT LINE AND AS PART OF THE CLOCK BALANCING. MOUNT THE BYPASS CAPACITORS CLOSE TO THE BASE RESISTOR FOR THE RESET TRANSISTOR, Q1, ON THE CONTROLLER PAGE.

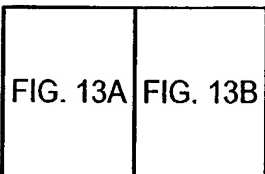


FIG. 13

FIG. 13A

1310

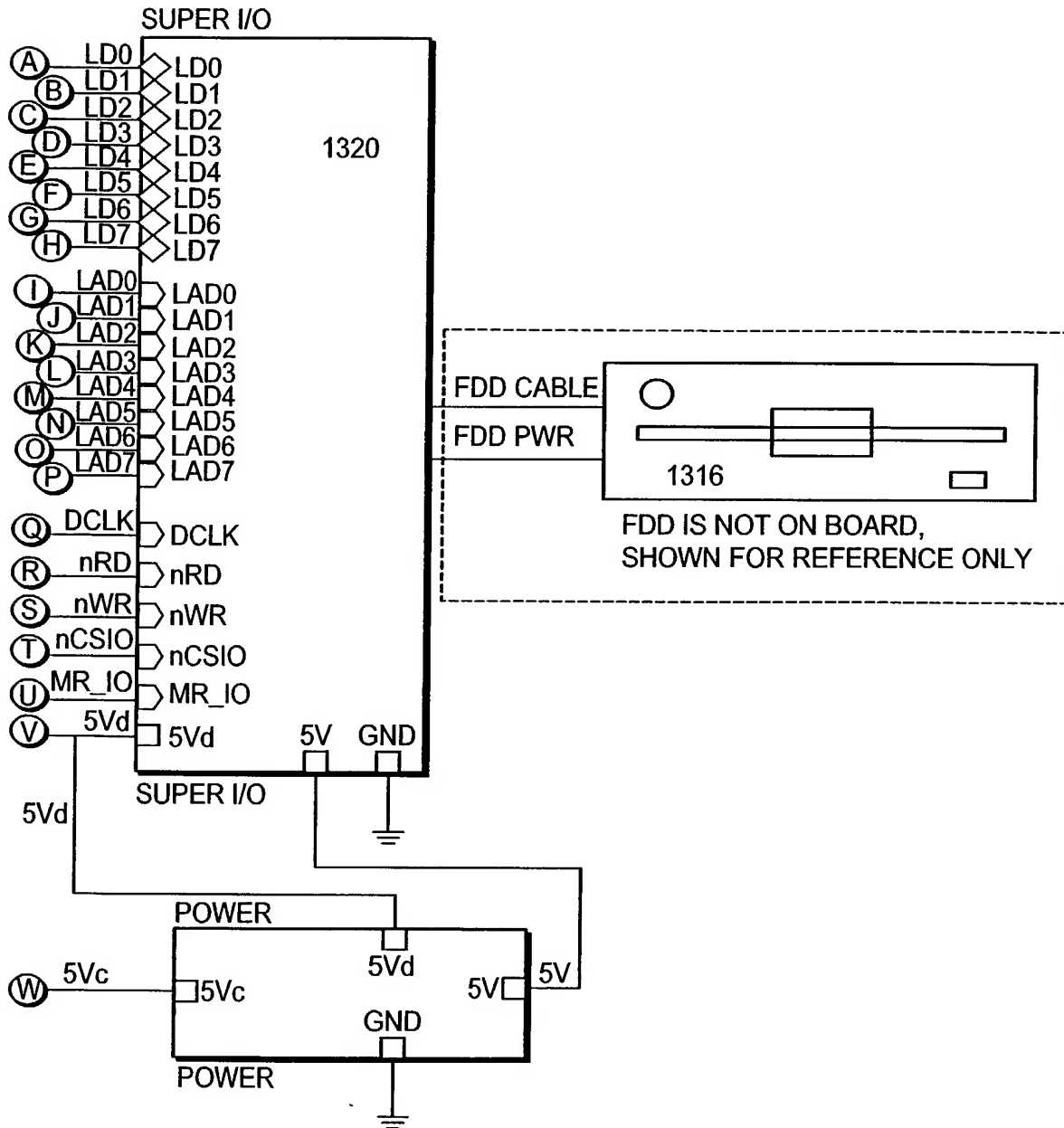


FIG. 13B

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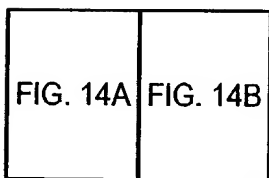
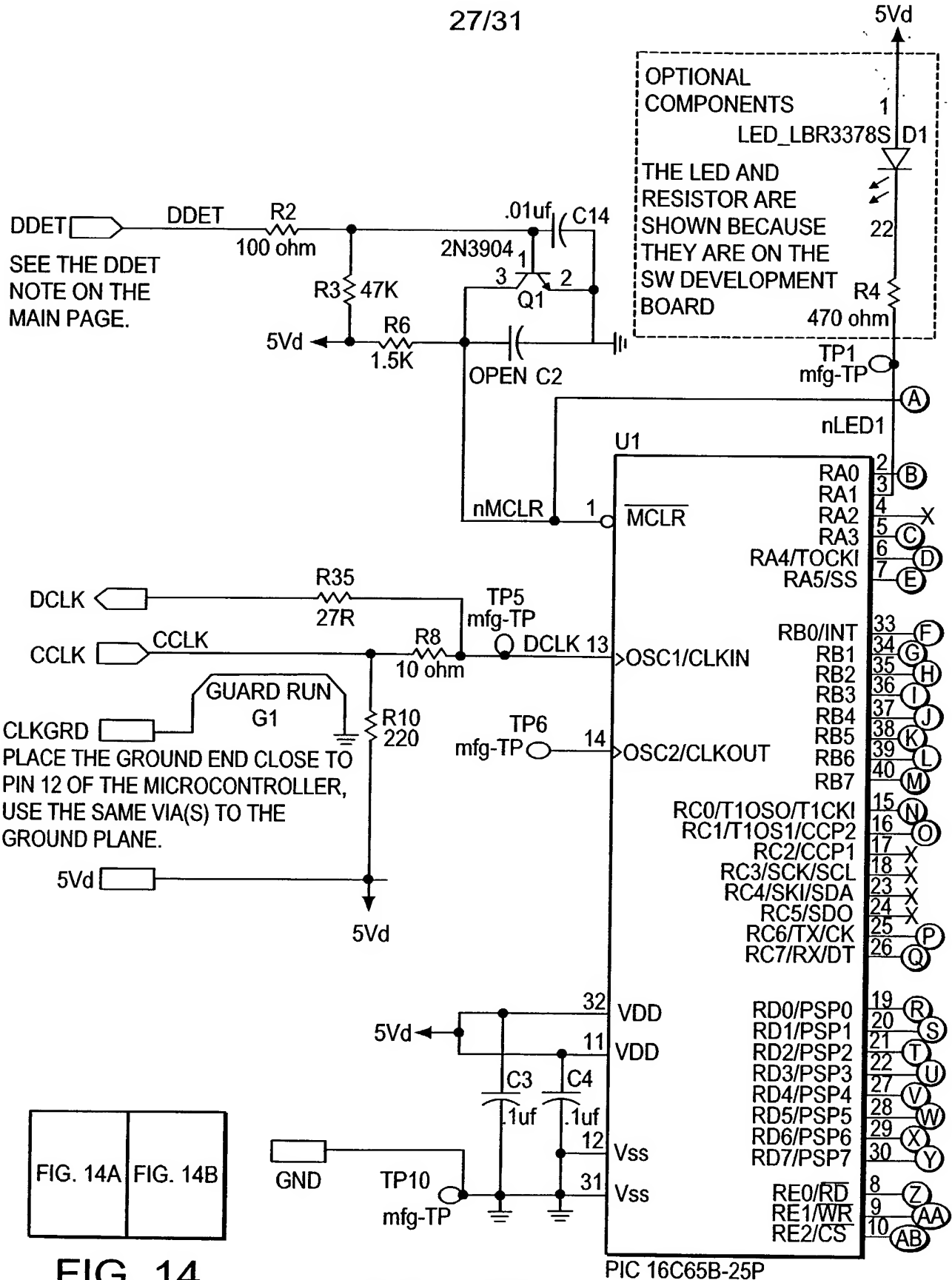


FIG. 14

FIG. 14A

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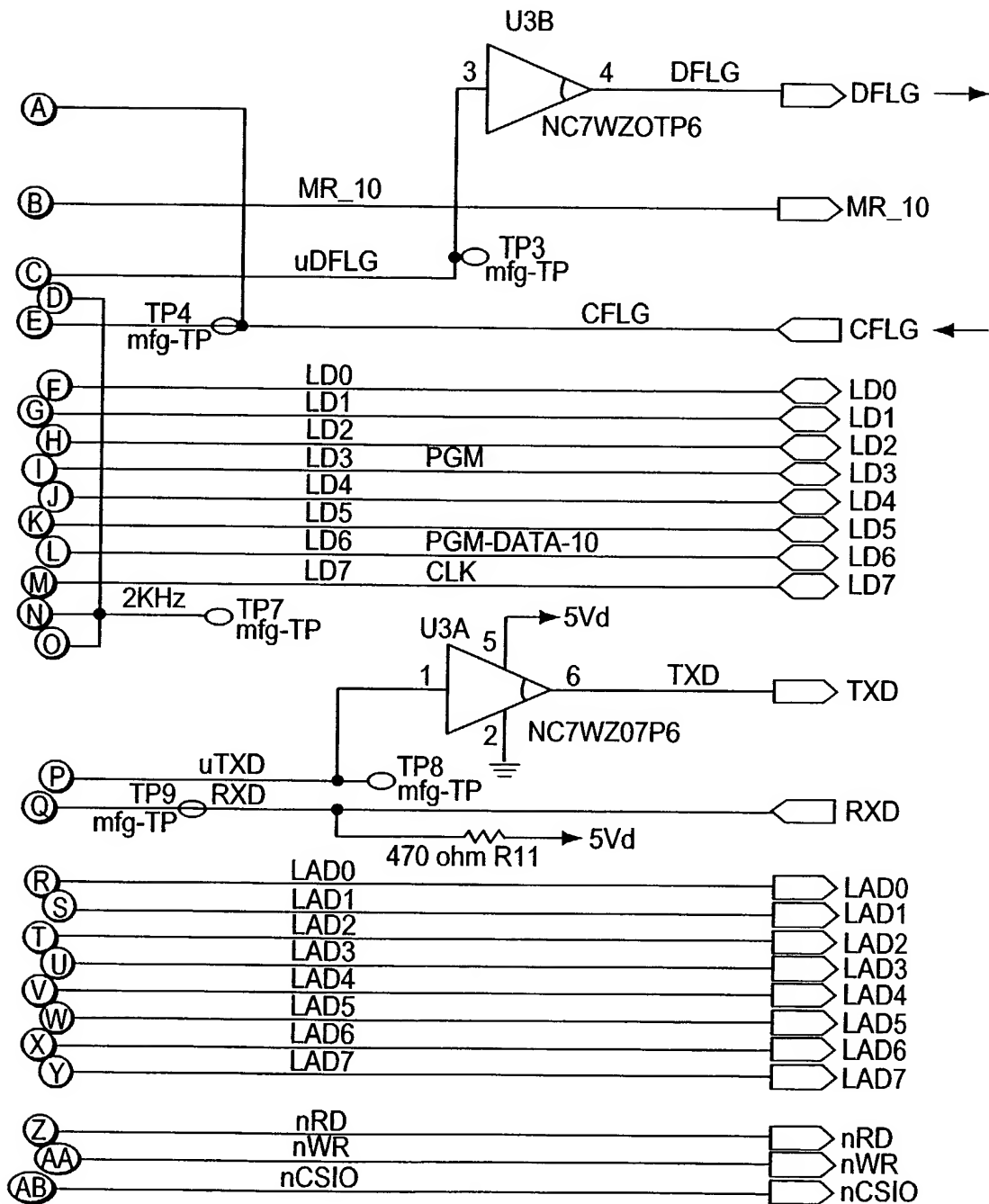
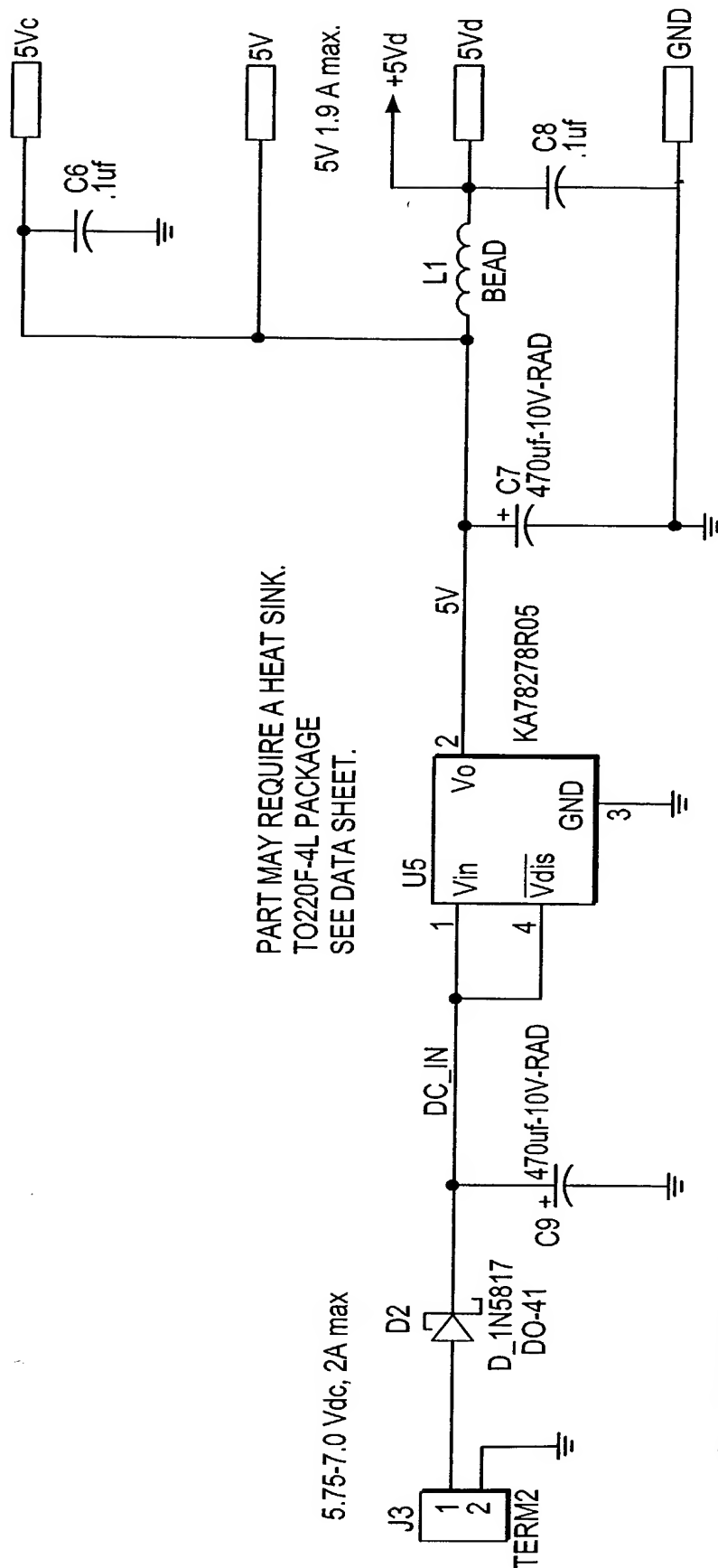


FIG. 14B



PART MAY REQUIRE A HEAT SINK.
TO220F-4L PACKAGE
SEE DATA SHEET.

NOTE POWER SUPPLY IS TO BE SIZED FOR THE PARTICULAR FLOPPY DISK
DRIVE'S MAXIMUM LOAD, ALLOW ~300 mA FOR OTHER LOADS.

SIZING AFFECTS CHOICE OF U5 AND ITS HEATSINK, THE FILTER CAPACITORS,
C7, C9 AND THE AC ADAPTER RATING.

FIG. 15

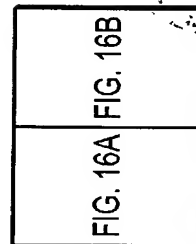


FIG. 16

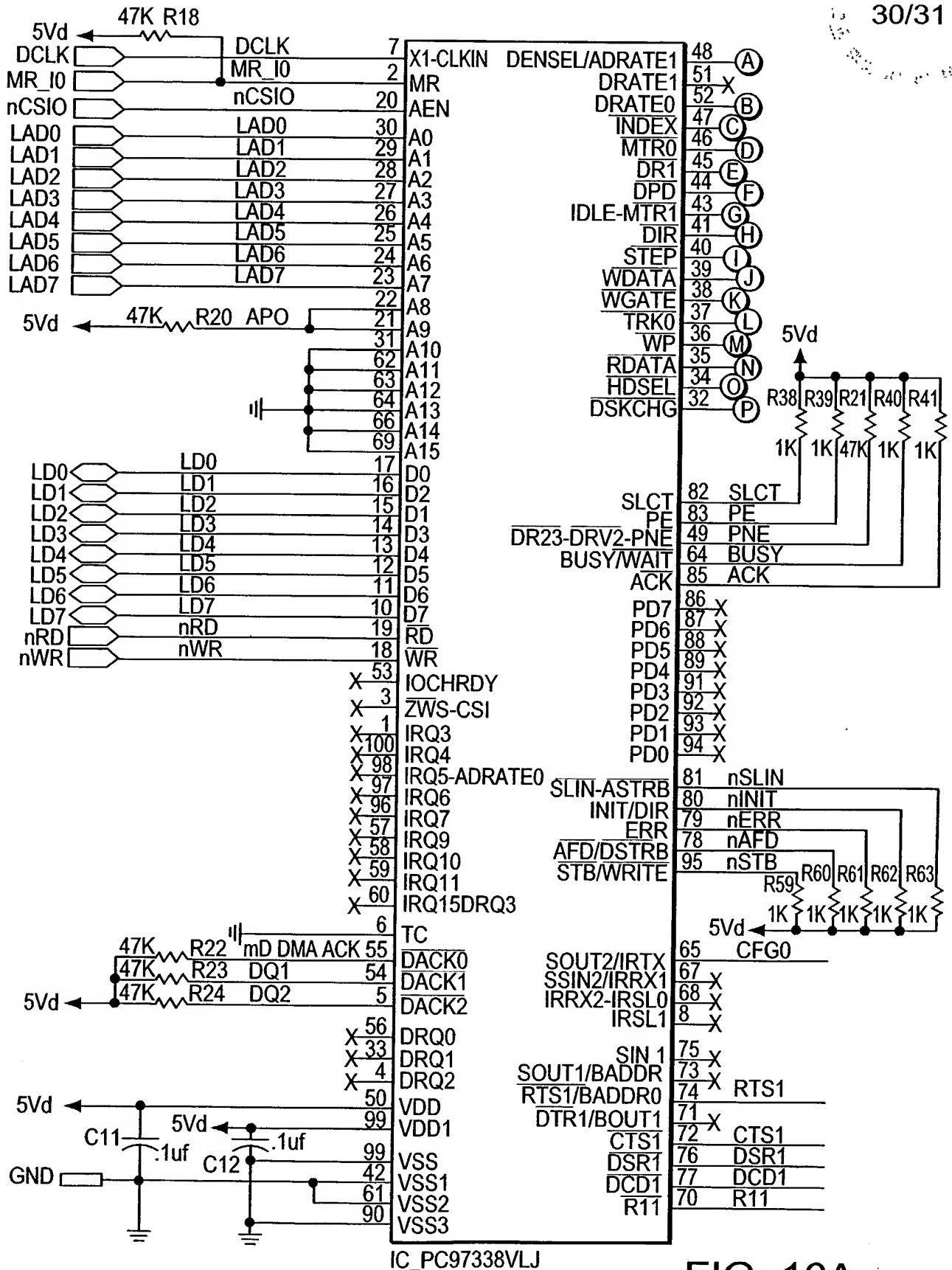


FIG. 16A

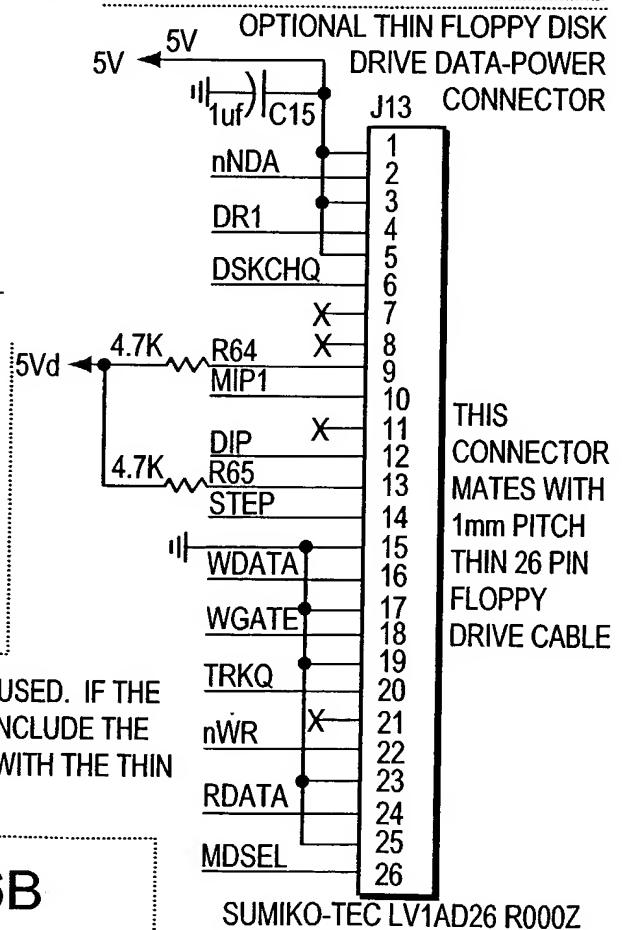
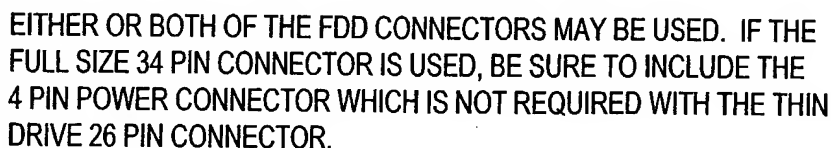


FIG. 16B